

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination DUNN ET AL.	
		Examiner George Fourson	Art Unit 2823	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-2006/0019494	01-2006	Cao et al.	438/680
*	B	US-2006/0027167	02-2006	Ishizaka et al.	118/715
*	C	US-2005/0101132	05-2005	Kim et al.	438/687
*	D	US-2004/0009307	01-2004	Koh et al.	427/569
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages
	U	Rossnagel, S.M., et al., "Plasma-Enhanced Atomic Layer Deposition of Ta and Ti for Interconnect Diffusion Barriers", J Vac Sci Technol B 18(4), Jul/Aug 2000, pp.2016-2020
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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